

Abstract

A semiconductor device and a method for manufacturing the semiconductor device mountable with high density, which includes a simplified process but is capable of reducing a defect rate. A plurality of identical memory chips are formed on a semiconductor wafer, and a go/no-go test is conducted on all the memory chips. The semiconductor wafer is cut and divided into pieces that each consists of one, or two, or four good memory chips, and they are mounted on a substrate to form a memory module.

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